

# L-934SURDK-TNR2.54

T-1 (3 mm) Tape and Reel LED Lamp

### **DESCRIPTIONS**

- The Hyper Red source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode
- Electrostatic discharge and power surge could damage the LEDs
- . It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- · All devices, equipments and machineries must be electrically grounded

# **FEATURES**

- For the use of automatic insertion machine
- 2.54 mm straight lead
- LED lamps also available in tape & box package
- Halogen-free
- RoHS compliant

#### **APPLICATIONS**

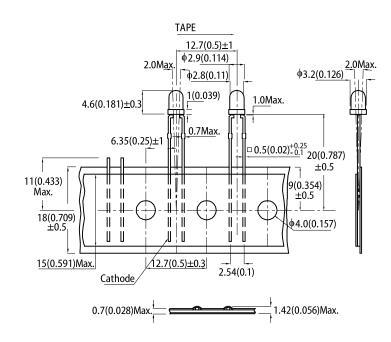
- · Status indicator
- Illuminator
- · Signage applications
- · Decorative and entertainment lighting
- · Commercial and residential architectural lighting

### **ATTENTION**

Observe precautions for handling electrostatic discharge sensitive devices



# **PACKAGE DIMENSIONS**



- Adl.

  Adl. dimensions are in millimeters (inches).

  Tolerance is ±0.25(0.01") unless otherwise noted.

  Lead spacing is measured where the leads emerge from the package.

  The specifications, characteristics and technical data described in the datasheet are subject to change

#### **SELECTION GUIDE**

	Emitting Color	Lens Type	Iv (mcd) @ 20mA [2]		Viewing Angle [1]	
Part Number	(Material)		Тур.	201/2		
L-934SURDK-TNR2.54	■ Hyper Red (AlGaInP)	Red Diffused	500	1200	50°	
			*200	*400	30	

toles.

6/1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

Luminous intensity / luminous flux: +/-15%.

Luminous intensity value is traceable to CIE127-2007 standards.





# ELECTRICAL / OPTICAL CHARACTERISTICS at T<sub>A</sub>=25°C

Parameter	Symbol	Funithing Colon	Value		Unit
Parameter	Symbol	Emitting Color	Тур. Мах.		
Wavelength at Peak Emission I <sub>F</sub> = 20mA	$\lambda_{peak}$	Hyper Red	645	-	nm
Dominant Wavelength I <sub>F</sub> = 20mA	λ <sub>dom</sub> <sup>[1]</sup>	Hyper Red	630	-	nm
Spectral Bandwidth at 50% $\Phi$ REL MAX I <sub>F</sub> = 20mA	Δλ	Hyper Red	28	-	nm
Capacitance	С	Hyper Red	35	-	pF
Forward Voltage I <sub>F</sub> = 20mA	V <sub>F</sub> <sup>[2]</sup>	Hyper Red	1.95	2.5	V
Reverse Current (V <sub>R</sub> = 5V)	I <sub>R</sub>	Hyper Red	-	10	μА
Temperature Coefficient of $\lambda_{\text{peak}}$ $I_F$ = 20mA, -10°C $\leq T \leq 85^{\circ}$ C	$TC_{\lambda peak}$	Hyper Red	0.14	-	nm/°C
Temperature Coefficient of $\lambda_{dom}$ $I_F$ = 20mA, -10°C $\leq T \leq 85^{\circ}$ C	$TC_{\lambdadom}$	Hyper Red	0.05	-	nm/°C
Temperature Coefficient of $V_F$ $I_F$ = 20mA, -10°C $\leq$ T $\leq$ 85°C	TC <sub>V</sub>	Hyper Red	-1.9	-	mV/°C

#### Notes:

# ABSOLUTE MAXIMUM RATINGS at T<sub>A</sub>=25°C

Parameter	Symbol	Value	Unit	
Power Dissipation	P <sub>D</sub>	75	mW	
Reverse Voltage	V <sub>R</sub>	5	V	
Junction Temperature	T <sub>j</sub>	115	°C	
Operating Temperature	T <sub>op</sub>	-40 To +85	°C	
Storage Temperature	T <sub>stg</sub>	-40 To +85	°C	
DC Forward Current	I <sub>F</sub>	30	mA	
Peak Forward Current	I <sub>FP</sub> <sup>[1]</sup>	185	mA	
Electrostatic Discharge Threshold (HBM)	-	3000	V	
Thermal Resistance (Junction / Ambient)	R <sub>th JA</sub> <sup>[2]</sup>	670	°C/W	
Thermal Resistance (Junction / Solder point)	R <sub>th JS</sub> <sup>[2]</sup>	440	°C/W	
Lead Solder Temperature [3]		260°C For 3 Seconds		
Lead Solder Temperature [4]		260°C For 5 Seconds		

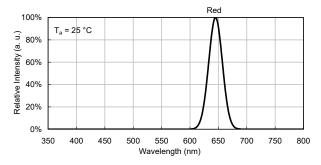
Notes:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2.  $R_{\text{In JA}}$ ,  $R_{\text{In JS}}$  Results from mounting on PC board FR4 (pad size  $\geq$  16 mm<sup>2</sup> per pad).
3. 2mm below package base.
4. 5mm below package base.
5. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

<sup>1.</sup> The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd:±1nm.)
2. Forward voltage: ±0.1V.
3. Wavelength value is traceable to CIE127-2007 standards.
4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

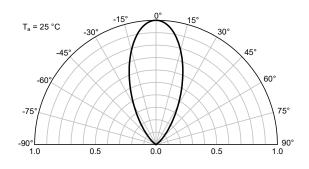


#### **TECHNICAL DATA**

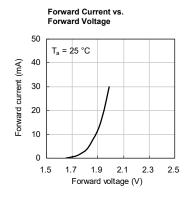
#### **RELATIVE INTENSITY vs. WAVELENGTH**

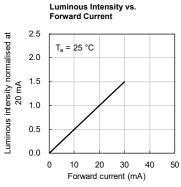


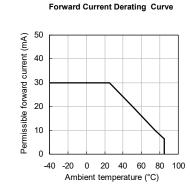
#### **SPATIAL DISTRIBUTION**

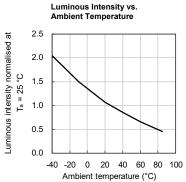


# **HYPER RED**

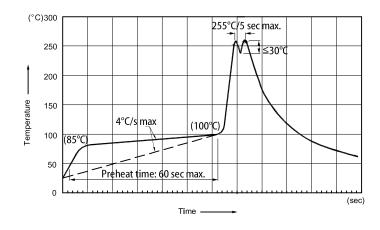








#### **RECOMMENDED WAVE SOLDERING PROFILE**



- Notes:

  1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C

  2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).

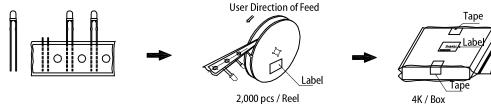
  3. Do not apply stress to the epoxy resin while the temperature is above 85°C.

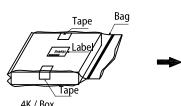
  4. Fixtures should not incur stress on the component when mounting and during soldering process.

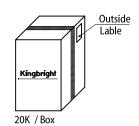
  5. SAC 305 solder alloy is recommended.

- 6. No more than one wave soldering pass.

#### **PACKING & LABEL SPECIFICATIONS**











#### **PRECAUTIONS**

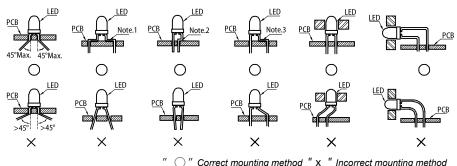
#### Storage conditions

- 1. Avoid continued exposure to the condensing moisture environment and keep the product away from rapid transitions in ambient
- 2. LEDs should be stored with temperature ≤ 30°C and relative humidity < 60%.
- 3. Product in the original sealed package is recommended to be assembled within 72 hours of opening. Product in opened package for more than a week should be baked for 30 (+10/-0) hours at 85 ~ 100°C.

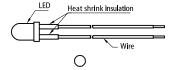
### **LED Mounting Method**

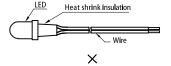
1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

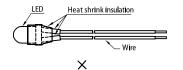
Note 1-3: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

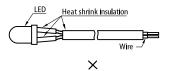


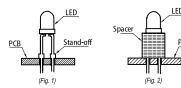
2. When soldering wires to the LED, each wire joint should be separately insulated with heat-shrink tube to prevent short-circuit contact. Do not bundle both wires in one heat shrink tube to avoid pinching the LED leads. Pinching stress on the LED leads may damage the internal structures and cause failure.









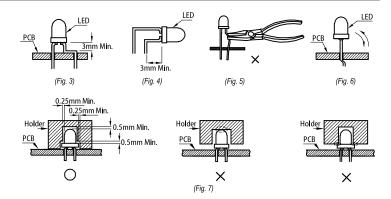


- 3. Use stand-offs (Fig.1) or spacers (Fig.2) to securely position the LED above the PCB.
- 4. Maintain a minimum of 3mm clearance between the base of the LED lens and the first lead bend (Fig. 3, Fig. 4).
- 5. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 5)

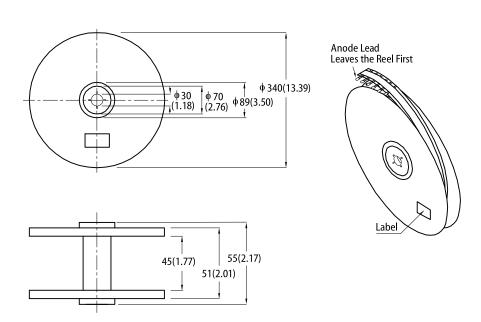


### **Lead Forming Procedures**

- 1. Do not bend the leads more than twice. (Fig. 6)
- 2. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering. (Fig. 7)
- 3. The tip of the soldering iron should never touch the lens epoxy.
- 4. Through-hole LEDs are incompatible with reflow soldering.
- 5. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.



#### **REEL DIMENSIONS**



### **PRECAUTIONARY NOTES**

- The information included in this document reflects representative usage scenarios and is intended for technical reference only.

  The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.
- The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening liabilities, such as automotive or medical usage, please consult with Kingbright representative for further assistance.

  The contents and information of this document may not be reproduced or re-transmitted without permission by Kingbright.
- All design applications should refer to Kingbright application notes available at http



# **X-ON Electronics**

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Kingbright manufacturer:

Other Similar products are found below:

AA1608CGSK AA1608QBS/D-10MAV AA1608SESK AA1608SURSK AA1608SYSK AA1608VBS/A1-10MAV AA1608ZGSK-10MAV

AA2214QBS/D AA2214SES/J4 AA2214SESK AA2214SURSK AA2214SYSK AA2214ZGS AA2810ACGSK AA2810AQBSD

AA2810ASES/J3 AA2810ASESK AA2810ASESK/J3 AA2810ASURSK AA2810ASYSJ3 AA2810ASYSK AA2810AVBS/D

AA2810AZGS AA2810AZGSK AA3021CGSK AA3021ES AA3021LSYSK/J3-TR AA3021LZGSK AA3021QBS/D AA3021SESK

AA3021SESK/J3-TR AA3021SGS AA3021SURSK AA3021SYSK AA3021VBS/D AA3021VRCBS/A AA3021YS AA3021ZGS

AA3021ZGSK AA3022ES-4.5SF AA3022SGS-4.5SF AA3022SRS-4.5SF AA3022YS-4.5SF AA3527ASESK-50MAV AA3527ASESK/J3-50MAV AA3527ASURS-50MAV AA3527ASYSK/J3-50MAV AA3527ASYSK/J3-50MAV AA3527AVBS/D-30MAV AA3527AZGSK-30MAV